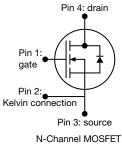
Vishay Siliconix

E Series Power MOSFET with Fast Body Diode



www.vishay.com



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	700				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.236			
Q _g max. (nC)	98				
Q _{gs} (nC)	11				
Q _{gd} (nC)	20				
Configuration	Single				

FEATURES

- Completely lead (Pb)-free device
- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH14N65EF-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_c = 25$ °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	650	v		
Gate-Source Voltage	V _{GS}	± 30	v			
Continuous Drain Current (T _J = 150 °C)	V_{GS} at 10 V $T_C = 25 \degree C$ $T_C = 100 \degree C$		15			
	V_{GS} at 10 V $T_C = 100 \text{ °C}$	I _D	9.5	А		
Pulsed Drain Current ^a	I _{DM}	36				
Linear Derating Factor			1.25	W/°C		
Single Pulse Avalanche Energy ^b		E _{AS}	226	mJ		
Maximum Power Dissipation	PD	156	W			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C		
Drain-Source Voltage Slope	T _J = 125 °C	d\//dt	70	1//22		
Reverse Diode dV/dt c		dV/dt	18	V/ns		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4 A.
- c. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C.

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COMPLIANT

HALOGEN

FREE

GREEN

(5-2008)



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THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	42		55				
Maximum Junction-to-Case (Drain)	R _{thJC}	0.57	0.57 0.80			°C/W		
SPECIFICATIONS ($T_J = 25 \ ^{\circ}C$, u	Inless otherwi	se noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static						•		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	250 µA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	I _D = 10 mA	-	0.73	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V_{GS} , $I_D = 2$	250 µA	2.0	-	4.0	V
Onto Oneman Lankana	_	\ \	$V_{\rm GS} = \pm 20$	V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}	\ \	$V_{\rm GS} = \pm 30$	V	-	-	± 1	μA
		V _{DS} =	520 V, V _G	_S = 0 V	-	-	1	
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 520 V	, V _{GS} = 0 V	′, T _J = 125 °C	-	-	500	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	I	_D = 7 A	-	0.236	0.271	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I _D	= 7 A	-	6.0	-	S
Dynamic						•		•
Input Capacitance	C _{iss}		V _{GS} = 0 V,		-	1749	-	
Output Capacitance	C _{oss}	$V_{GS} = 0.0$ V, $V_{DS} = 100$ V, f = 1 MHz		-	82	-		
Reverse Transfer Capacitance	C _{rss}			-	4	-		
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V_{DS} = 0 V to 520 V, V_{GS} = 0 V		-	57	-	pF	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	228	-	1	
Total Gate Charge	Qg				-	49	98	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V I _D = 7 A, V _{DS} = 520 V		-	11	-	nC	
Gate-Drain Charge	Q _{gd}	1			-	20	-	1
Turn-On Delay Time	t _{d(on)}				-	21	42	
Rise Time	t _r	V _{DD} =	V _{DD} = 520 V, I _D = 7 A,		-	28	56	
Turn-Off Delay Time	t _{d(off)}	V _{GS} =	= 10 V, R _g =	= 9.1 Ω	-	56	84	ns
Fall Time	t _f	1			-	29	58	1
Gate Input Resistance	R _g	f = 1 MHz, open drain		0.35	0.70	1.4	Ω	
Drain-Source Body Diode Characteristic	cs							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	A	
Pulsed Diode Forward Current	I _{SM}			-	-	36		
Diode Forward Voltage	V _{SD}	T _J = 25 °C	$T_{J} = 25 \text{ °C}, I_{S} = 7 \text{ A}, V_{GS} = 0 \text{ V}$		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = I _S = 7 A, dl/dt = 100 A/µs, V _B = 25 V		7.4	-	120	240	ns
Reverse Recovery Charge	Q _{rr}			-	0.6	1.2	μC	
Reverse Recovery Current	I _{RRM}		$u/u = 100 \text{ A/}\mu\text{s}, v_{\text{R}} = 25 \text{ v}$		-	10	-	Α

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

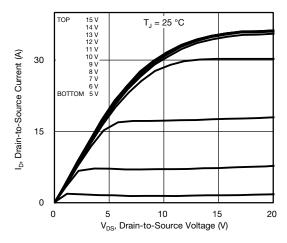


Fig. 1 - Typical Output Characteristics

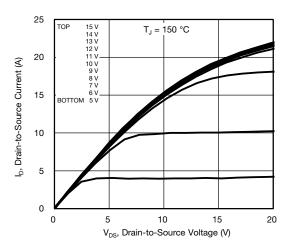
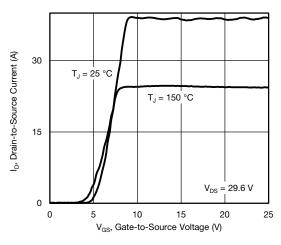


Fig. 2 - Typical Output Characteristics





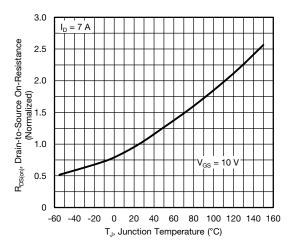


Fig. 4 - Normalized On-Resistance vs. Temperature

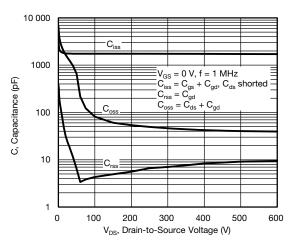


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

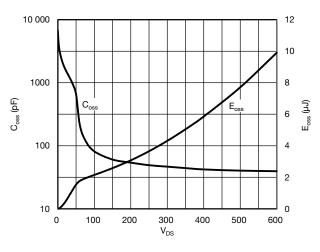


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}

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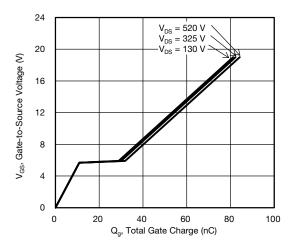


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

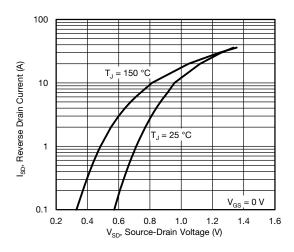


Fig. 8 - Typical Source-Drain Diode Forward Voltage

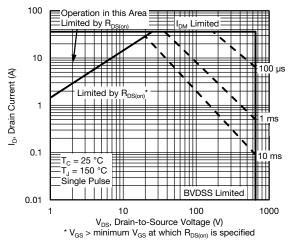


Fig. 9 - Maximum Safe Operating Area

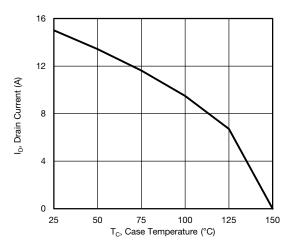


Fig. 10 - Maximum Drain Current vs. Case Temperature

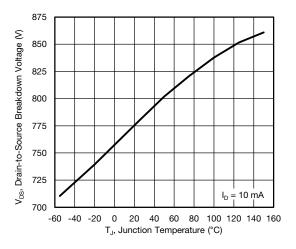
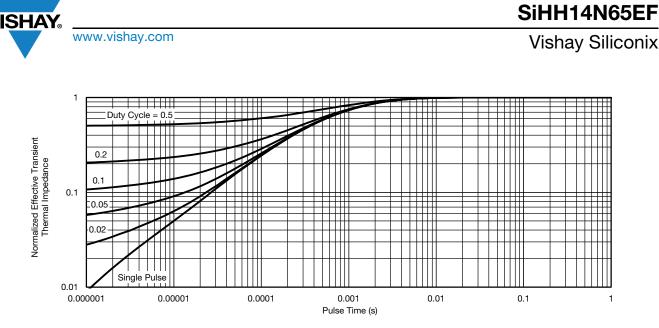


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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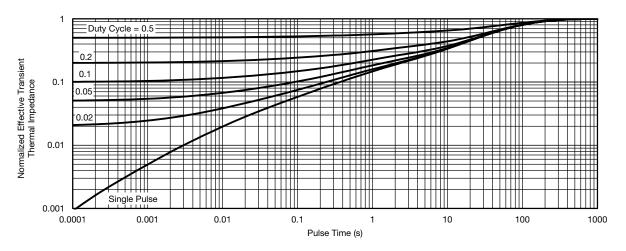


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

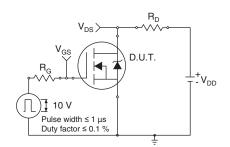


Fig. 14 - Switching Time Test Circuit

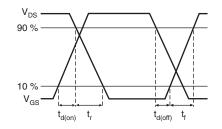


Fig. 15 - Switching Time Waveforms



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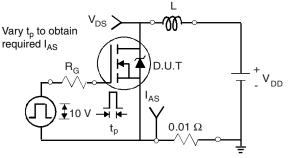


Fig. 16 - Unclamped Inductive Test Circuit

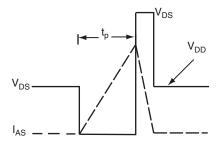


Fig. 17 - Unclamped Inductive Waveforms

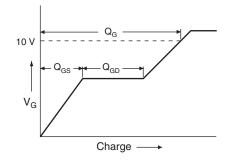


Fig. 18 - Basic Gate Charge Waveform

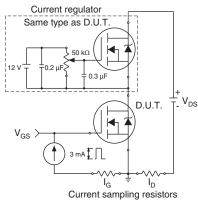


Fig. 19 - Gate Charge Test Circuit

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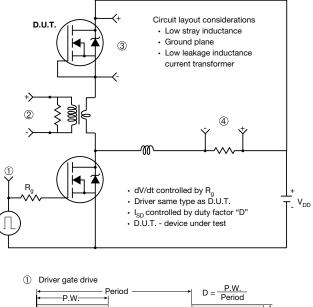
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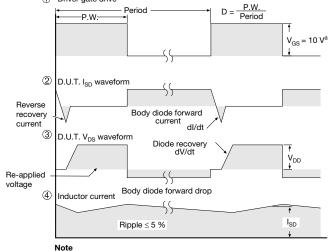
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Peak Diode Recovery dV/dt Test Circuit





a. $V_{GS} = 5 V$ for logic level devices

Fig. 20 - For N-Channel

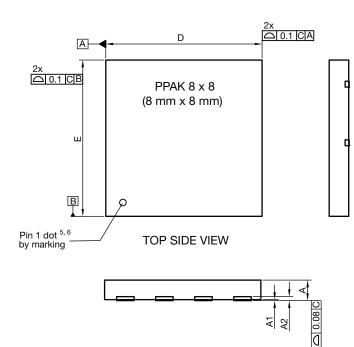
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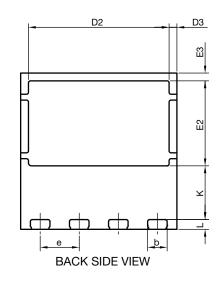
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PowerPAK[®] 8 x 8 Case Outline





DIM	MILLIMETERS			INCHES			
DIM. MIN.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2		020 ref.		0.008 ref.			
b	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3		0.40 BSC) BSC 0.016 BSC				
е		2.00 BSC		0.079 BSC			
E	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3		0.40 BSC		0.016 BSC			
К	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N ⁽³⁾	8			8			

Notes

⁽¹⁾ Use millimeters as the primary measurement

⁽²⁾ Dimensioning and tolerances conform to ASME Y14.5 M - 1994

⁽³⁾ N is the number of terminals

⁽⁴⁾ The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body

⁽⁵⁾ Exact shape and size of this feature is optional

ECN: E20-0518-Rev. B, 28-Sep-2020 DWG: 6041

Revision: 28-Sep-2020

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Recommended Minimum PADs for PowerPAK[®] 8 mm x 8 mm



Dimensions in millimeters

Document Number: 68441



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